AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings of claims in the application:

Claim 1 (Currently Amended): A hotmelt adhesive composition structure, comprising:

an upper dot and a lower dot on a substrate;

for the coating and/or lamination of sheetlike structures,

wherein the upper dot and the lower dot are based on comprise an amine-terminated crosslinkable copolyamide and the lower dot further comprises a crosslinker and an acrylic and/or polyurethane dispersion.

Claim 2 (Currently Amended): A The hotmelt adhesive eomposition structure as claimed in claim 1, wherein the copolyamide is an amine-regulated terminated copolyamide powder having a melting range of 90 to 150°C and a solution viscosity eta rel in the range from 1.2 to 1.7.

Claims 3-5 (Canceled):

Claim 6 (Currently Amended): A The hotmelt adhesive composition structure as claimed in claim 1, wherein the crosslinking component comes from the group of the isocyanates and has more than two reactive groups per molecule.

Claim 7 (Currently Amended): A The hotmelt adhesive composition structure as claimed in claim 1, wherein the isocyanate has a melting range of from 100 to 130°C.

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Claim 8 (Currently Amended): A <u>The hotmelt adhesive composition structure</u> as claimed <u>in claim 1</u>, wherein an epoxide having a melting range of from 90 to 130°C, a molecular weight range from 2000 to 6000 and more than two epoxide groups per molecule is employed as crosslinking component.

Claim 9 (Currently Amended): A <u>The hotmelt adhesive composition structure</u> as claimed <u>in claim 1</u>, wherein a pulverulent free or blocked isocyanate is employed as crosslinking component.

Claim 10 (Currently Amended): A <u>The hotmelt adhesive composition structure</u> as claimed <u>in claim 1</u>, wherein the amine-<u>regulated terminated copolyamides in the upper dot and lower dot have different melting temperatures or viscosities.</u>

Claim 11 (Currently Amended): A <u>The hotmelt adhesive emposition structure</u> as claimed <u>in claim 1</u>, wherein the crosslinking component is an epichlorohydrin.

Claim 12 (Currently Amended): A <u>The hotmelt adhesive composition structure</u> as claimed <u>in claim 1</u>, wherein the acrylic component is a di- and/or triacrylate.

Claim 13 (Currently Amended): A <u>The hotmelt adhesive emposition structure</u> as claimed <u>in claim 1</u>, wherein the reactive amine-<u>regulated terminated copolyamide</u> is employed as base dot for the double dot technology, as a strikethrough barrier.

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Claim 14 (Currently Amended): A <u>The</u> hotmelt adhesive composition <u>structure</u> as claimed <u>in</u> claim 1, wherein the base dot consists of a passivated isocyanate and an amine-regulated <u>terminated</u> copolyamide and is applied in halftone formation as a paste.

Claim 15 (Currently Amended): A <u>The hotmelt adhesive composition structure</u> as claimed in claim 1, wherein the crosslinking reaction is accelerated by catalysts.

Claim 16 (Currently Amended): A <u>The hotmelt adhesive composition structure</u> as claimed <u>in claim 1</u>, wherein the copolyamides are based on lactames (LL, CL), dimer fatty acids and corresponding dicarboxylic acids and diamines having chain lengths of C2 to C15 and piperazine.

Claim 17 (Currently Amended): A method of using the hotmelt adhesive emposition structure as claimed in claim 1 for the coating and/or lamination of sheetlike structures.

Claim 18 (Currently Amended): An interlining material for clothing, which has been provided with a hotmelt adhesive eomposition structure as claimed in claim 1.